DATA SHEET

BFS520
NPN 9 GHz wideband transistor

Product specification

September 1995

NPN 9 GHz wideband transistor BFS520

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability
- SOT323 envelope.

DESCRIPTION

NPN transistor in a plastic SOT323 envelope.

It is intended for wideband applications such as satellite TV tuners, cellular phones, cordless phones, pagers etc., with signal frequencies up to 2 GHz.

PINNING

PIN	DESCRIPTION
	Code: N2
1	base
2	emitter
3	collector

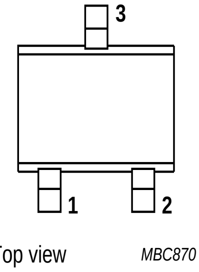


Fig.1 SOT323.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CES}	collector-emitter voltage	R_{BE} = 0	–	–	15	V
I_C	DC collector current		–	–	70	mA
P_{tot}	total power dissipation	up to T_s = 118 °C; note 1	–	–	300	mW
h_{FE}	DC current gain	I_C = 20 mA; V_{CE} = 6 V; T_j = 25 °C	60	120	250	
f_T	transition frequency	I_C = 20 mA; V_{CE} = 6 V; f = 1 GHz; T_{amb} = 25 °C	–	9	–	GHz
G_{UM}	maximum unilateral power gain	I_c = 20 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	15	–	dB
F	noise figure	I_c = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	1.1	1.6	dB

LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	20	V
V_{CES}	collector-emitter voltage	R_{BE} = 0	–	15	V
V_{EBO}	emitter-base voltage	open collector	–	2.5	V
I_C	DC collector current		–	70	mA
P_{tot}	total power dissipation	up to T_s = 118 °C; note 1	–	300	mW
T_{stg}	storage temperature		–65	150	°C
T_j	junction temperature		–	175	°C

Note

1. T_s is the temperature at the soldering point of the collector tab.

THERMAL RESISTANCE

SYMBOL	PARAMETER	CONDITIONS	THERMAL RESISTANCE
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	up to T_s = 118 °C; note 1	190 K/W

Note

1. T_s is the temperature at the soldering point of the collector tab.

CHARACTERISTICS

T_j = 25 °C, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	I_E = 0; V_{CE} = 6 V	–	–	50	nA
h_{FE}	DC current gain	I_C = 20mA; V_{CE} = 6 V	60	120	250	
C_e	emitter capacitance	$I_C = i_c$ = 0; V_{EB} = 0.5 V; f = 1 MHz	–	1	–	pF
C_c	collector capacitance	$I_E = i_e$ = 0; V_{CB} = 6 V; f = 1 MHz	–	0.5	–	pF
C_{re}	feedback capacitance	I_C = 0; V_{CB} = 6 V; f = 1 MHz	–	0.4	–	pF
f_T	transition frequency	I_C = 20 mA; V_{CE} = 6 V; f = 1 GHz; T_{amb} = 25 °C	–	9	–	GHz
G_{UM}	maximum unilateral power gain (note 1)	I_C = 20 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	15	–	dB
		I_C = 20 mA; V_{CE} = 6 V; f = 2 GHz; T_{amb} = 25 °C	–	9	–	dB
$\|S_{21}\|^2$	insertion power gain	I_C = 20 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	13	14	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	1.1	1.6	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 20 mA; V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C	–	1.6	2.1	dB
		$\Gamma_s = \Gamma_{opt}$; I_C = 5 mA; V_{CE} = 6 V; f = 2 GHz; T_{amb} = 25 °C	–	1.9	–	dB
P_{L1}	output power at 1 dB gain compression	I_c = 20 mA; V_{CE} = 6 V; R_L = 50 Ω; f = 900 MHz; T_{amb} = 25 °C	–	17	–	dBm
ITO	third order intercept point	note 2	–	26	–	dBm

Notes

1. G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero and

$$G_{UM} = 10 \log \frac{|S_{21}|^2}{(1-|S_{11}|^2)(1-|S_{22}|^2)} \text{ dB.}$$

2. I_C = 20 mA; V_{CE} = 6 V; R_L = 50 Ω; f = 900 MHz; T_{amb} = 25 °C;
f_p = 900 MHz; f_q = 902 MHz; measured at $f_{(2p-q)}$ = 898 MHz and at $f_{(2q-p)}$ = 904 MHz.

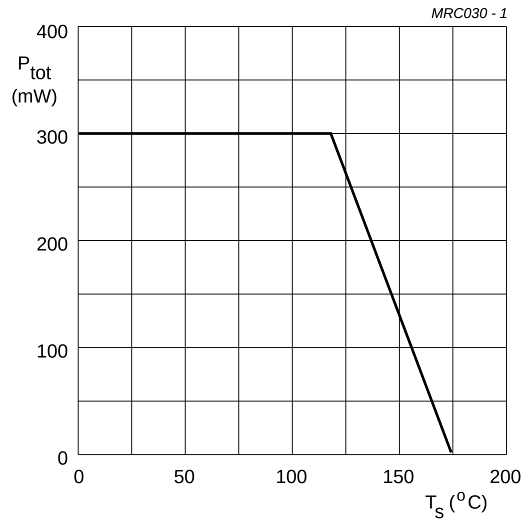
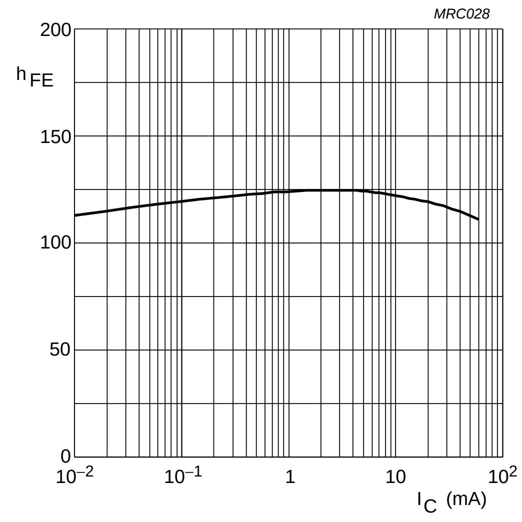
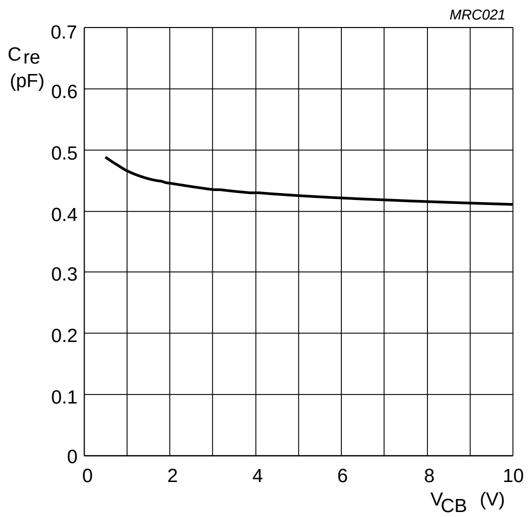


Fig.2 Power derating curve.



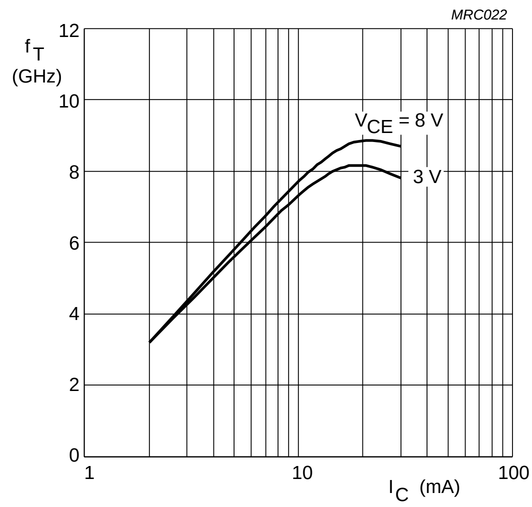
V_{CE} = 6 V; T_j = 25 °C.

Fig.3 DC current gain as a function of collector current.



I_C = 0; f = 1 MHz.

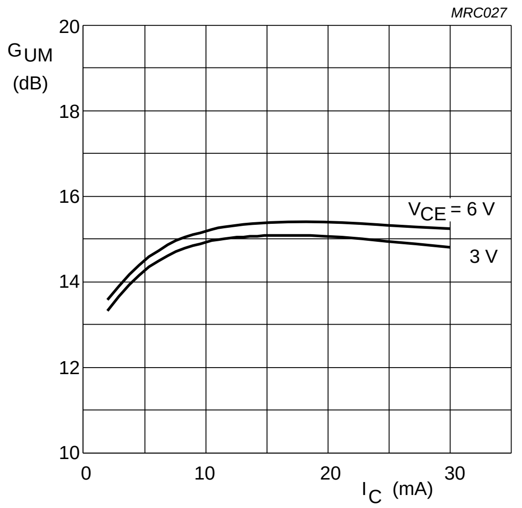
Fig.4 Feedback capacitance as a function of collector-base voltage.



f = 1 GHz; T_{amb} = 25 °C.

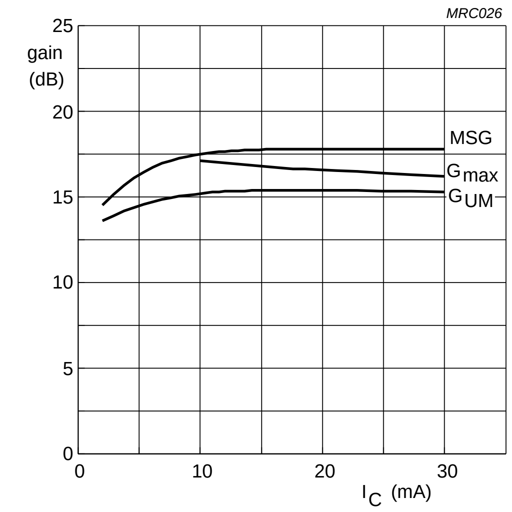
Fig.5 Transition frequency as a function of collector current.

In Figs 6 to 9, G_{UM} = maximum unilateral power gain; MSG = maximum stable gain; G_{max} = maximum available gain.



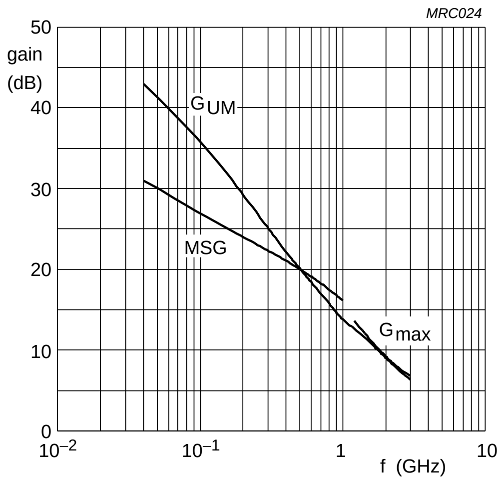
V_{CE} = 6 V; f = 900 MHz; T_{amb} = 25 °C.

Fig.6 Maximum unilateral power gain as a function of collector current.



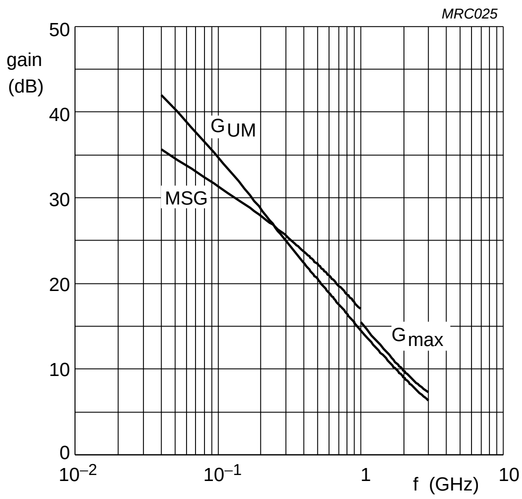
V_{CE} = 6 V; f = 2 GHz; T_{amb} = 25 °C.

Fig.7 Gain as a function of collector current.



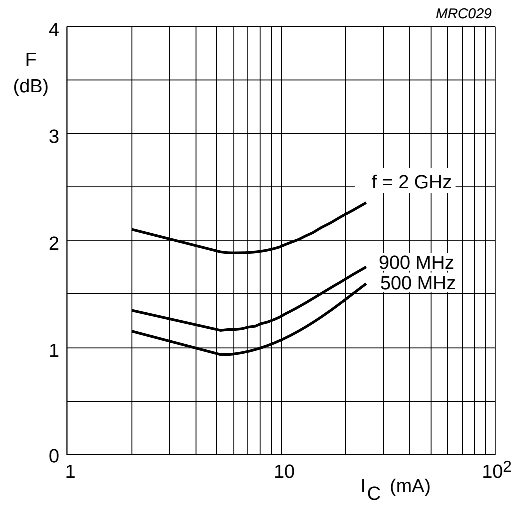
I_C = 5 mA; V_{CE} = 6 V; T_{amb} = 25 °C.

Fig.8 Gain as a function of frequency.



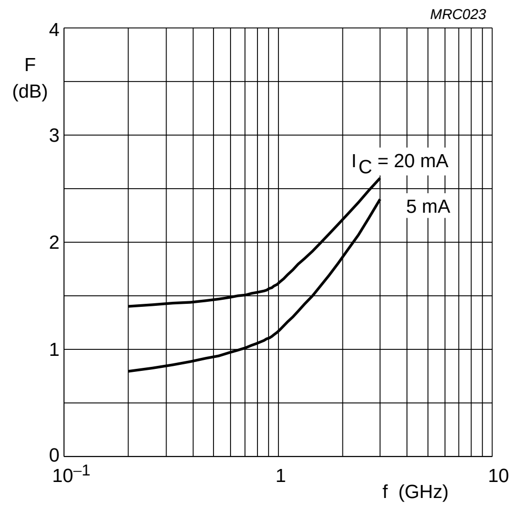
I_C = 20 mA; V_{CE} = 6 V; T_{amb} = 25 °C.

Fig.9 Gain as a function of frequency.



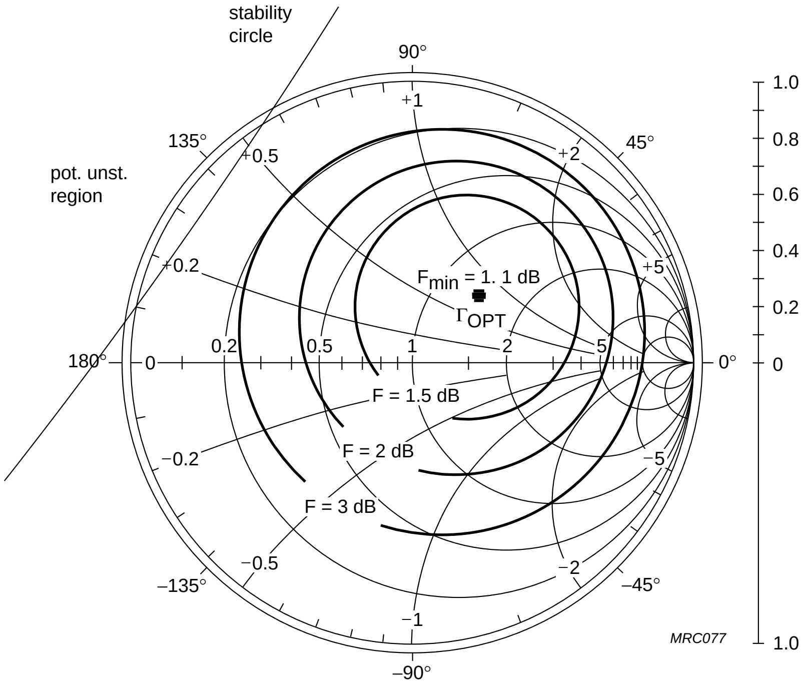
V_{CE} = 6 V; T_{amb} = 25 °C.

Fig.10 Minimum noise figure as a function of collector current.



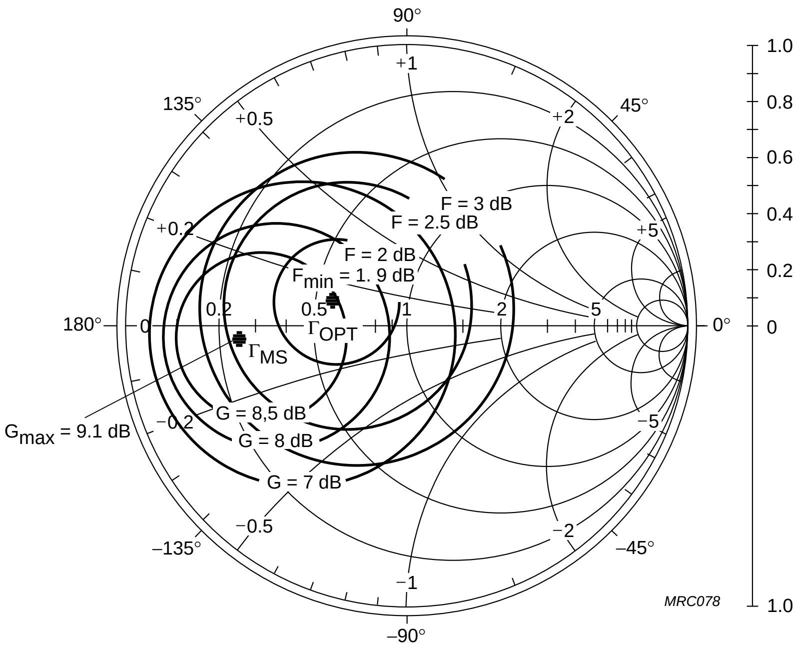
V_{CE} = 6 V; T_{amb} = 25 °C.

Fig.11 Minimum noise figure as a function of frequency.



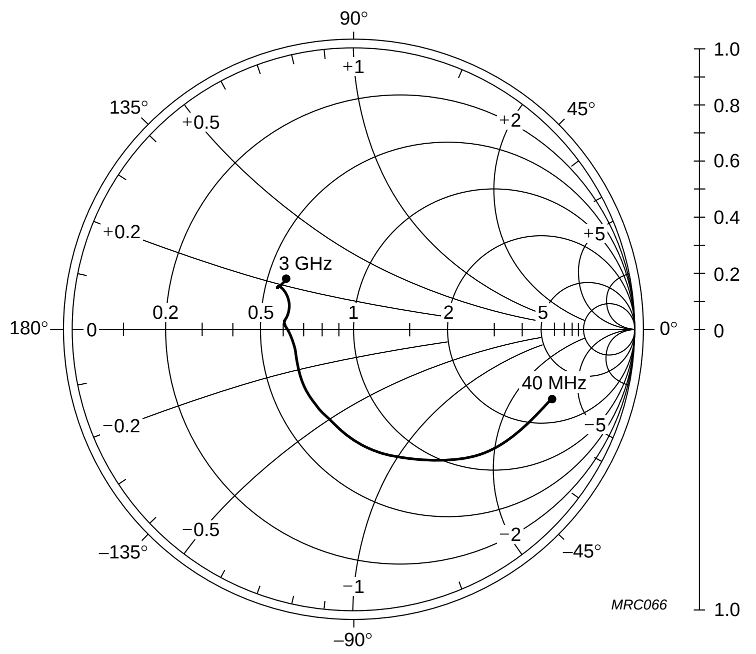
I_C = 5 mA; V_{CE} = 6 V;
f = 900 MHz; Z_o = 50 Ω.

Fig.12 Noise circle.



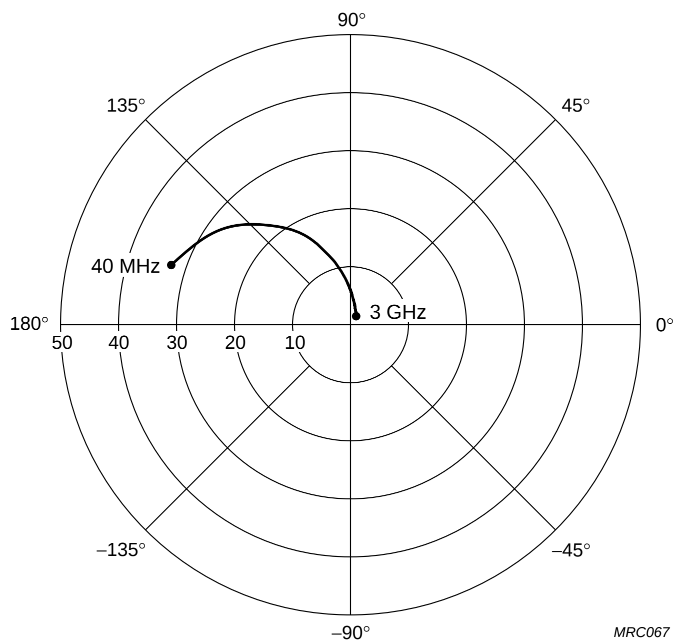
I_C = 5 mA; V_{CE} = 6 V;
f = 2 GHz; Z_o = 50 Ω.

Fig.13 Noise circle.



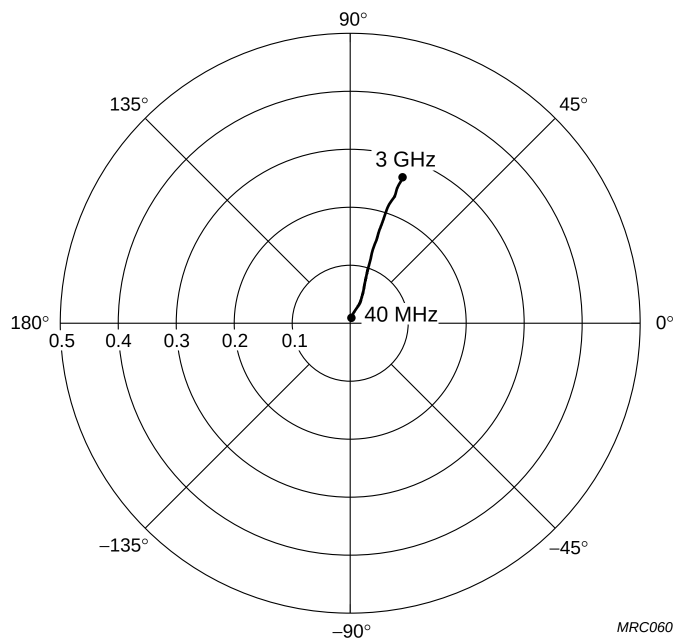
I_C = 20 mA; V_{CE} = 6 V;
Z_o = 50 Ω.

Fig.14 Common emitter input reflection coefficient (S_{11}).



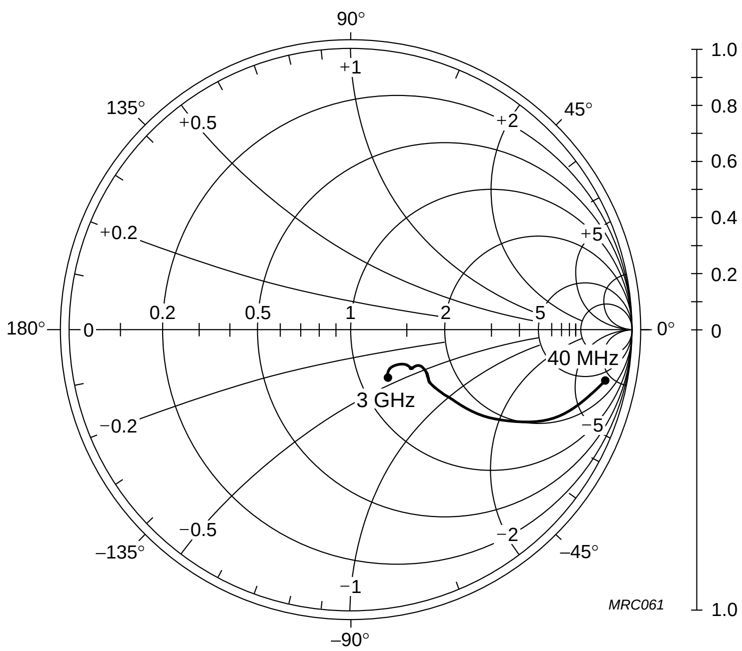
I_C = 20 mA; V_{CE} = 6 V.

Fig.15 Common emitter forward transmission coefficient (S_{21}).



I_C = 20 mA; V_{CE} = 6 V.

Fig.16 Common emitter reverse transmission coefficient (S_{12}).

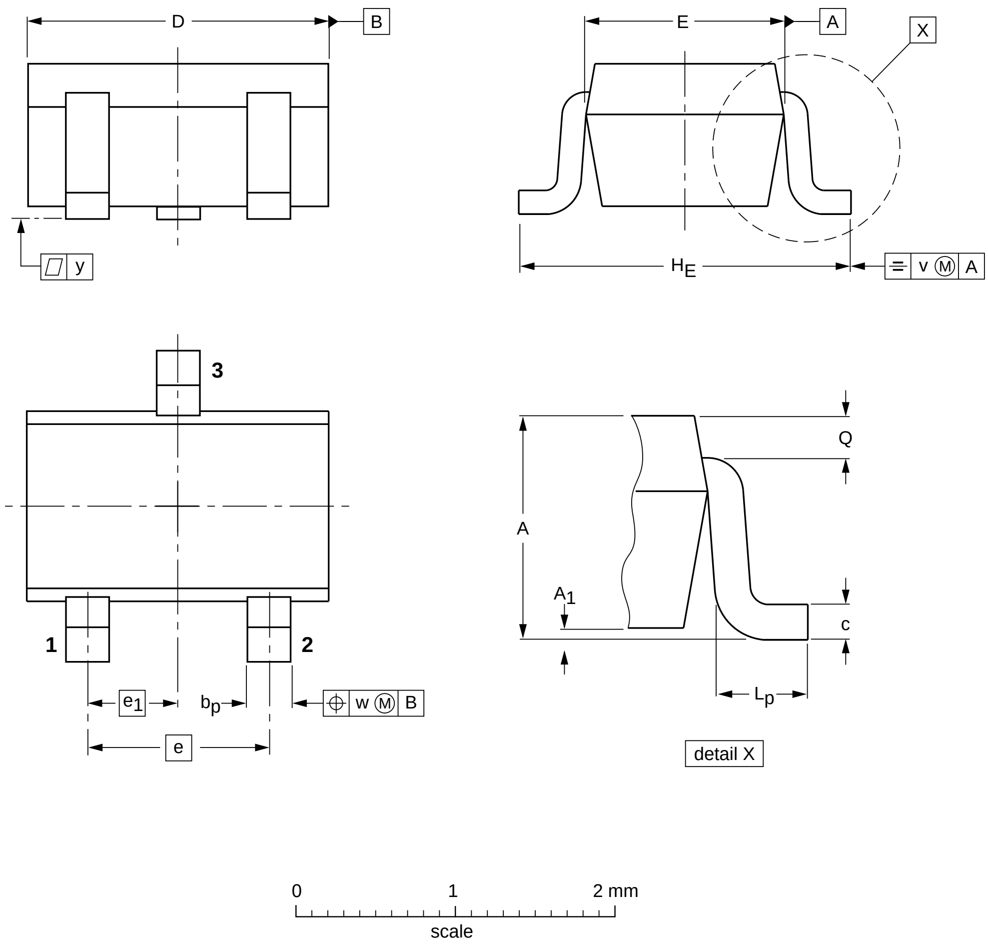


I_C = 20 mA; V_{CE} = 6 V;
Z_o = 50 Ω.

Fig.17 Common emitter output reflection coefficient (S_{22}).

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads **SOT323**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			~~04-11-04~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS(1)	PRODUCT STATUS(2)	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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